CLAIMS

1. A silicon containing curing composition comprising at least one silicon containing polymer selected from the following components (A), (B), and (C) and the following component (D) as a catalyst, provided that the composition contains both the components (A) and (B) when the component (C) is absent:

(A) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of $Si\text{-}R^1$, $Si\text{-}O\text{-}R^2$, and $Si\text{-}R^3\text{-}OCOC(R^4)=CH_2$, wherein R^1 and R^2 each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group; R^3 represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group; and R^4 represents hydrogen or a methyl group,

having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

(B) A silicon containing polymer having an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less.

(C) A silicon containing polymer having at least one kind of a reactive group A' selected from the group consisting of $Si\text{-}R^1$, $Si\text{-}O\text{-}R^2$, and $Si\text{-}R^3\text{-}OCOC(R^4)=CH_2$, wherein R^1 and R^2 each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group; R^3 represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group; and R^4 represents hydrogen or a methyl group,

and an Si-H group, having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular

weight is 1000 or less.

(D) A platinum-based catalyst as a catalyst for curing reaction.

2. The silicon containing curing composition according to claim 1, wherein the total aryl group and arylene group content of the total silicon containing polymers as components (A), (B), and (C) is 0.1% to 50% by weight.

3. The silicon containing curing composition according to claim 1 or 2, which further comprises a metal oxide fine powder as component (E).

4. A cured product obtained by heat curing the silicon containing curing composition according to any one of claims 1 to 3.